

ABSTRACT

Methods for mounting electrical components on a substrate and securely retaining the components are described. The methods include altering solder paste compositions, interposed between component retentive pins and retentive through holes, during a reflow process. Electronic assemblies including circuit boards and electrical components mounted thereto are also described. In one of the electronic assembly embodiments, materials originally associated with a mounted electrical component migrate into solder paste coupling the electrical component to the circuit board.